

Breakout Board Errata Memo

ECE 492 - Spring 2015

Latest Revision: 5 May 2015
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Abstract

This memo will detail the physical errata associated with the layout of the LFEV - 2015 TSV system's Breakout Board (BoB).

Errata Summary

After initial fabrication of the LFEV 2015 version of the Breakout Board, it was realized that there were some layout errors on the board. These errors include through holes that were incorrectly placed and needed to be isolated, as well as a missing trace.

NOTE: All errata have been corrected in the most updated versions of the Gerber files and schematics for the BoB, as well as having been physically fixed by William Stathis on the working BoB used in LFEV TSV 2015's system. Ordering new boards for future use will require no changes to be made; however, if future teams wish to utilize the 4 boards we purchased in 2015, these errata should be handled.

1. Isolation of the through hole near U6 and L2.
2. Isolation of the through hole near C2.
3. Isolation of multiple through holes near U1, U8, and U11.
4. Missing connection between U17 the AMS I2C port.

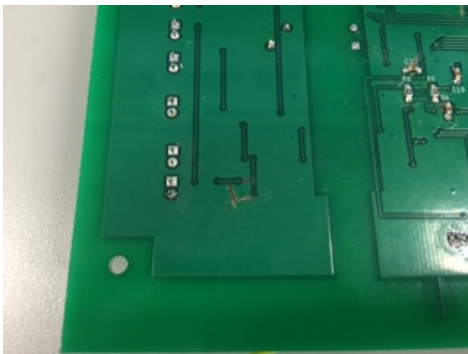


Figure 1. Errata 1.

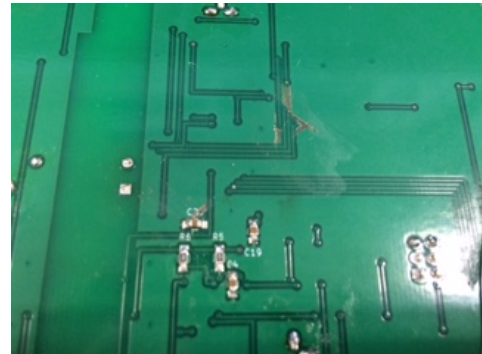


Figure 2. Errata 2 & 3

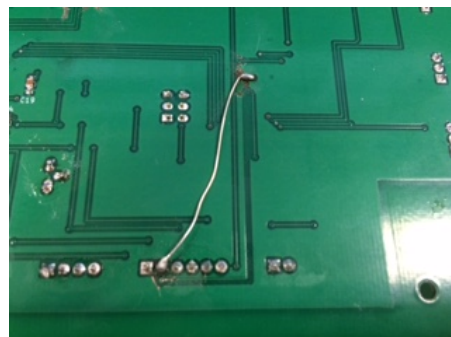


Figure 3. Errata 4